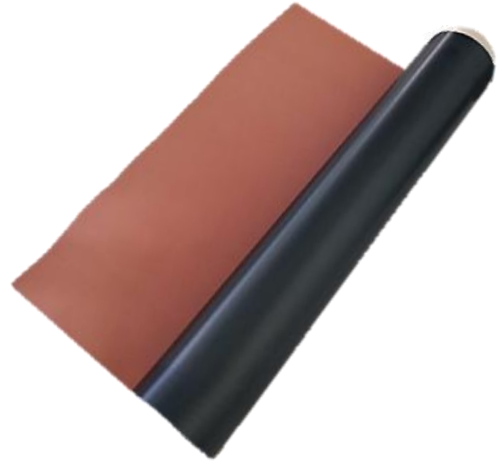


石墨銅箔 GOS-P Series

Graphite Copper Foil



型號 Model No.	銅箔厚度 Copper Foil Thickness (μm)
GOS-P35	35
GOS-P70	70
GOS-P100	100
GOS-P140	140

物性表參考 Physical Properties Table

(以 35μm 銅箔石墨片為例 Based on 35μm Copper Foil Graphite Sheet for Reference.)

項目 Project	數值 Value
基材厚度 Substrate thickness	0.035 mm
密度 Density	8.2 g/cm ³
耐溫範圍 Heat resistance	400°C
熱傳導率-水平 Thermal conductivity – Horizontal	400 W/m·K
熱傳導率-垂直 Thermal conductivity – Vertical	320 W/m·K
導電率 Electrical conductivity	2×10 ⁶ S/m
耐折彎次數 (180°折彎) Bend resistance (180° bend cycles)	100,000 次以上
抗拉強度 (水平方向) Tensile strength (horizontal direction)	≥28 (Mpa)

加工方式

Processing method

可卷對卷加工模切、無需包邊、折彎完全不脆裂、不用額外加 Film 材，可重工。

Roll-to-roll die cutting, no edge wrapping required, bends without cracking, no additional film material needed, and reworkable.

